

8

7

6

5

4

3

DRW NO.
C-379-5181-500

SH
1

REV
C

TABLE 1	
PART NUMBER ①	DESCRIPTION
379-5181-X00	PLUG ASSY. 6 PAIR, 3 MM HIGH (REDUCED WIPE), 10 WAFERS, 100 OHMS NO LOSSY
379-5281-X00	PLUG ASSY. 6 PAIR, 3 MM HIGH (REDUCED WIPE), 10 WAFERS, 85 OHMS NO LOSSY

ISOMETRIC VIEW

SCALE 6/1

NOTES:

①

ASSEMBLY PART NUMBER VARIES WITH PLATING OPTION AS FOLLOWS:
FOR NI SULFAMATE UNDERPLATE, 8TH DIGIT OF P/N IS 2.
FOR NANO NI UNDERPLATE, 8TH DIGIT OF P/N IS 4.

2.

MAT'L:
HOUSING/WAFERS - LCP.
VACUUM CAP - SST.
CONTACTS - HIGH PERFORMANCE COPPER ALLOY, PER MTS-506.

3.

0.71 DIA SOLDER SPHERES WILL NOT BE PERFECTLY SPHERICAL AFTER REFLOW ATTACHMENT.

④

HOLES RECOMMENDED FOR VISUAL INSPECTION OF CONNECTOR ALIGNMENT AFTER PLACEMENT AND BEFORE REFLOW. HOLES ARE NOT REQUIRED.

⑤

SOLDER BALL PROTRUSION BELOW HOUSING.

⑥

SEE TECHNICAL BULLETIN TB-2241 FOR DETAILED SMT PROCESSING AND PCB FOOT PRINT RECOMMENDATIONS.

⑦

MAXIMUM CO-PLANARITY OF THE BALL FIELD.

⑧

MAXIMUM RADIAL TRUE POSITION OF ANY SOLDER BALL IN RELATION TO AN IDEAL BEST FIT GRID.

9.

TOLERANCES DO NOT APPLY TO REFERENCE DIMENSIONS SHOWN IN "()" OR BASIC DIMENSIONS SHOWN IN "□".

10.

REFER TO FILE 379-5X81-XX0.STP FOR SIMPLIFIED 3D MODEL OF ASSEMBLY.

⑪

TOOLING HOLES USED FOR INTERNAL PROCESS ALIGNMENT AND NOT REQUIRED FOR SMT PROCESS ALIGNMENT. QUANTITY OF TOOLING HOLES IS OPTIONAL, AT MANUFACTURERS DISCRETION.

ZONE	REV	SCR NUMBER	DESCRIPTION	BY	DATE	APPROVED
ALL	A	DMAN-8W SRMQ.VER01	NEW RELEASE	D.MALOON	08/03/12	D.McNAMARA
SH1-2 SH1,B6	B	DMAN-95KKF2.VER01	MOLDED VAC CAP REPLACED WITH SST CAP CHANGED NOTE 2: VAC CAP MAT'L WAS LCP	D.MALOON	03/07/13	D.McNAMARA
SH1 SH3 SH4	C	MCHH-9UJSA4.VER01	ADDED NOTE 11, ADDED HOLES NOT NECESSARY TO NOTE 4. REMOVED A DRILLED HOLE ON SHEETS 3&4	M.CHARETH	03/13/15	D.McNAMARA

①

ASSEMBLY PART NUMBER VARIES WITH PLATING OPTION AS FOLLOWS:
FOR NI SULFAMATE UNDERPLATE, 8TH DIGIT OF P/N IS 2.
FOR NANO NI UNDERPLATE, 8TH DIGIT OF P/N IS 4.

2.

MAT'L:
HOUSING/WAFERS - LCP.
VACUUM CAP - SST.
CONTACTS - HIGH PERFORMANCE COPPER ALLOY, PER MTS-506.

3.

0.71 DIA SOLDER SPHERES WILL NOT BE PERFECTLY SPHERICAL AFTER REFLOW ATTACHMENT.

④

HOLES RECOMMENDED FOR VISUAL INSPECTION OF CONNECTOR ALIGNMENT AFTER PLACEMENT AND BEFORE REFLOW. HOLES ARE NOT REQUIRED.

⑤

SOLDER BALL PROTRUSION BELOW HOUSING.

⑥

SEE TECHNICAL BULLETIN TB-2241 FOR DETAILED SMT PROCESSING AND PCB FOOT PRINT RECOMMENDATIONS.

⑦

MAXIMUM CO-PLANARITY OF THE BALL FIELD.

⑧

MAXIMUM RADIAL TRUE POSITION OF ANY SOLDER BALL IN RELATION TO AN IDEAL BEST FIT GRID.

9.

TOLERANCES DO NOT APPLY TO REFERENCE DIMENSIONS SHOWN IN "()" OR BASIC DIMENSIONS SHOWN IN "□".

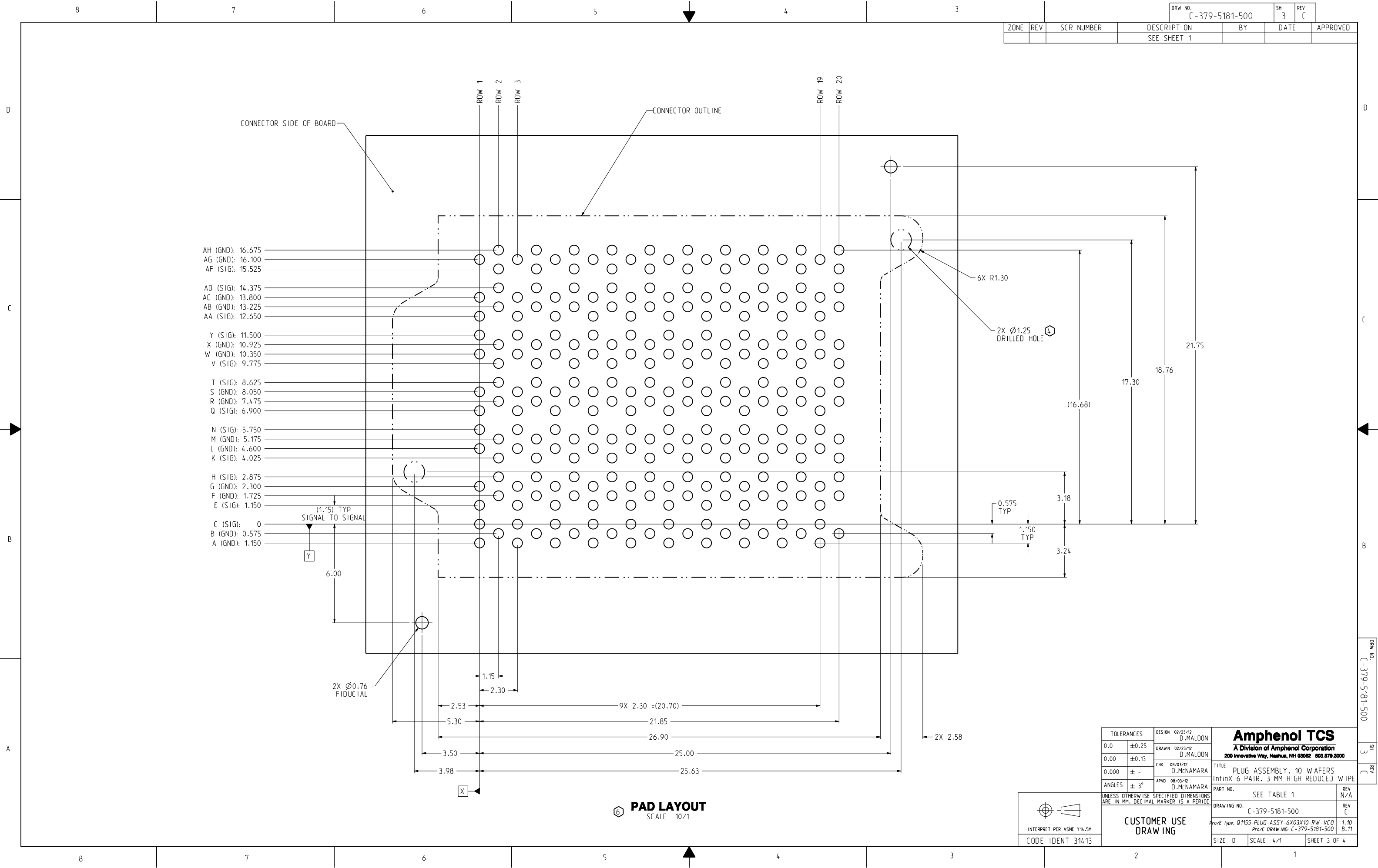
10.

REFER TO FILE 379-5X81-XX0.STP FOR SIMPLIFIED 3D MODEL OF ASSEMBLY.

⑪

TOOLING HOLES USED FOR INTERNAL PROCESS ALIGNMENT AND NOT REQUIRED FOR SMT PROCESS ALIGNMENT. QUANTITY OF TOOLING HOLES IS OPTIONAL, AT MANUFACTURERS DISCRETION.

TOLERANCES		DESIGN 02/23/12 D.MALOON	Amphenol TCS A Division of Amphenol Corporation 200 Innovative Way, Nashua, NH 03062 603.879.3000	
0.0	±0.25	DRAWN 02/23/12 D.MALOON	TITLE PLUG ASSEMBLY, 10 WAFERS InfinX 6 PAIR, 3 MM HIGH REDUCED WIPE	
0.00	±0.13	CHK 08/03/12 D.McNAMARA		
0.000	± -	APVD 08/03/12 D.McNAMARA		
ANGLES	± 3°			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM. DECIMAL MARKER IS A PERIOD		PART NO. SEE TABLE 1		REV N/A
① ASSEMBLY PART NUMBER VARIES WITH PLATING OPTION AS FOLLOWS: FOR NI SULFAMATE UNDERPLATE, 8TH DIGIT OF P/N IS 2. FOR NANO NI UNDERPLATE, 8TH DIGIT OF P/N IS 4. 2. MAT'L: HOUSING/WAFERS - LCP. VACUUM CAP - SST. CONTACTS - HIGH PERFORMANCE COPPER ALLOY, PER MTS-506. 3. 0.71 DIA SOLDER SPHERES WILL NOT BE PERFECTLY SPHERICAL AFTER REFLOW ATTACHMENT. ④ HOLES RECOMMENDED FOR VISUAL INSPECTION OF CONNECTOR ALIGNMENT AFTER PLACEMENT AND BEFORE REFLOW. HOLES ARE NOT REQUIRED. ⑤ SOLDER BALL PROTRUSION BELOW HOUSING. ⑥ SEE TECHNICAL BULLETIN TB-2241 FOR DETAILED SMT PROCESSING AND PCB FOOT PRINT RECOMMENDATIONS. ⑦ MAXIMUM CO-PLANARITY OF THE BALL FIELD. ⑧ MAXIMUM RADIAL TRUE POSITION OF ANY SOLDER BALL IN RELATION TO AN IDEAL BEST FIT GRID. 9. TOLERANCES DO NOT APPLY TO REFERENCE DIMENSIONS SHOWN IN "()" OR BASIC DIMENSIONS SHOWN IN "□". 10. REFER TO FILE 379-5X81-XX0.STP FOR SIMPLIFIED 3D MODEL OF ASSEMBLY. ⑪ TOOLING HOLES USED FOR INTERNAL PROCESS ALIGNMENT AND NOT REQUIRED FOR SMT PROCESS ALIGNMENT. QUANTITY OF TOOLING HOLES IS OPTIONAL, AT MANUFACTURERS DISCRETION.		DRAWING NO. C-379-5181-500		REV C
		CODE IDENT 31413		SIZE D SCALE 5/1 SHEET 1 OF 4



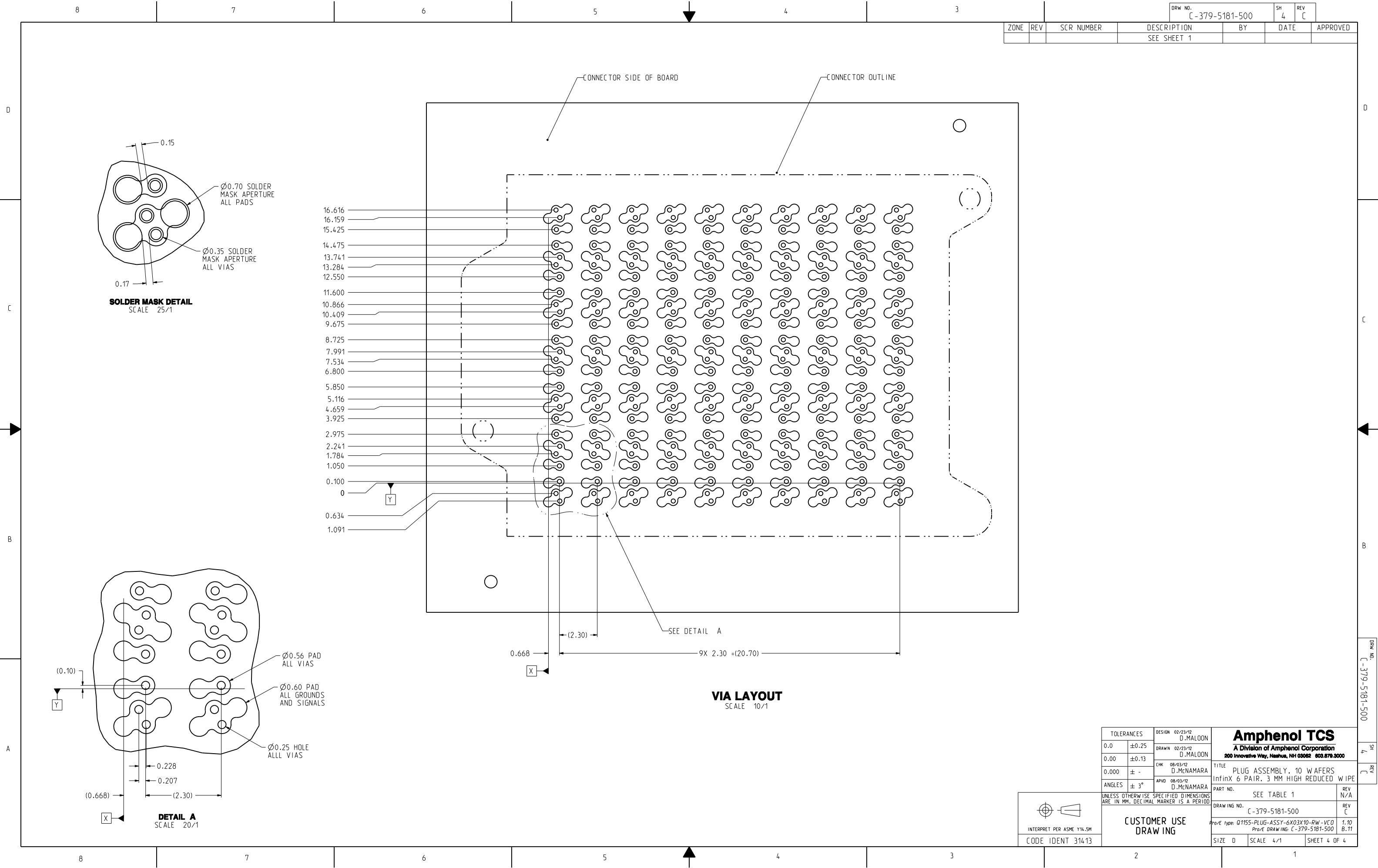
ZONE	REV	SCR NUMBER	DESCRIPTION	BY	DATE	APPROVED
			SEE SHEET 1			

DRW NO.	SH	REV
C-379-5181-500	3	C

TOLERANCES		DESIGN 02/23/12 D.MALOON	Amphenol TCS A Division of Amphenol Corporation 200 Innovative Way, Nashua, NH 03062 603.879.3000	
0.0	±0.25	DRAWN 02/23/12 D.MALOON		
0.00	±0.13	CHK 08/03/12 D.McNAMARA		
0.000	± -	APVD 08/03/12 D.McNAMARA		
ANGLES	± 3°	TITLE PLUG ASSEMBLY, 10 WAFERS InfinX 6 PAIR, 3 MM HIGH REDUCED WIPE		REV N/A
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM. DECIMAL MARKER IS A PERIOD			PART NO. SEE TABLE 1	REV C
DRAWING NO. C-379-5181-500			PRO/E Type: 01155-PLUG-ASSY-6X03X10-RW-VCO PRO/E DRAWING: C-379-5181-500	1.10 B.11
SIZE D		SCALE 4/1	SHEET 3 OF 4	

	INTERPRET PER ASME Y14.5M
CODE IDENT 314.13	

PAD LAYOUT
SCALE 10/1



Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

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<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9